

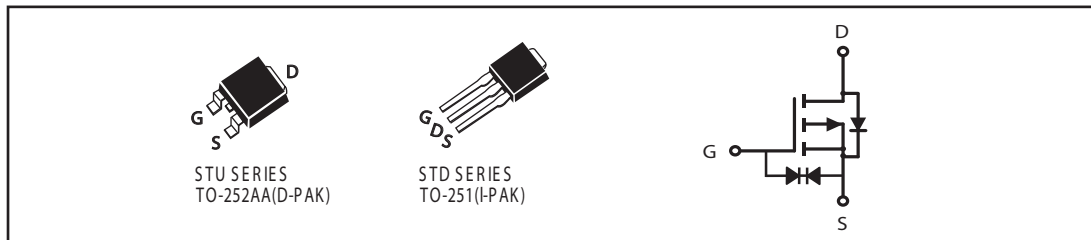


## P-Channel Logic Level Enhancement Mode Field Effect Transistor

PRODUCT SUMMARY		
V <sub>DSS</sub>	I <sub>D</sub>	R <sub>DS(ON)</sub> (mΩ) Max
-40V	-40A	9 @ V <sub>GS</sub> = -10V
		12 @ V <sub>GS</sub> = -4.5V

### FEATURES

- Super high dense cell design for low R<sub>DS(ON)</sub>.
- Rugged and reliable.
- Surface Mount Package.
- ESD Protected



### ABSOLUTE MAXIMUM RATINGS (T<sub>A</sub>=25°C unless otherwise noted)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage	V <sub>DS</sub>	-40	V	
Gate-Source Voltage	V <sub>GS</sub>	±20	V	
Drain Current-Continuous <sup>a</sup> @ T <sub>a</sub>	I <sub>D</sub>	25°C	-40	A
		70°C	-32	A
-Pulsed <sup>b</sup>	I <sub>DM</sub>	-100	A	
Drain-Source Diode Forward Current <sup>a</sup>	I <sub>S</sub>	-10	A	
Maximum Power Dissipation <sup>a</sup>	P <sub>D</sub>	T <sub>a</sub> = 25°C	50	W
		T <sub>a</sub> =70°C	35	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to 175	°C	

### THERMAL CHARACTERISTICS

Thermal Resistance, Junction-to-Case	R <sub>θJC</sub>	3	°C/W
Thermal Resistance, Junction-to-Ambient	R <sub>θJA</sub>	50	°C/W

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P-Channel ELECTRICAL CHARACTERISTICS (TA = 25°C unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ <sup>c</sup>	Max	Unit
<b>OFF CHARACTERISTICS</b>						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = -250uA	-40			V
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -32V, V <sub>GS</sub> = 0V			-1	uA
Gate-Body Leakage	I <sub>GSS</sub>	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V			±10	uA
<b>ON CHARACTERISTICS<sup>a</sup></b>						
Gate Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = -250uA	-1.0	-1.5	-3.0	V
Drain-Source On-State Resistance	R <sub>DS(ON)</sub>	V <sub>GS</sub> = -10V, I <sub>D</sub> = -14A		7	9	m ohm
		V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -10A		9.5	12	m ohm
On-State Drain Current	I <sub>D(ON)</sub>	V <sub>DS</sub> = -5V, V <sub>GS</sub> = -10V	30			A
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -14A		9		S
<b>DYNAMIC CHARACTERISTICS<sup>b</sup></b>						
Input Capacitance	C <sub>ISS</sub>	V <sub>DS</sub> = -15V, V <sub>GS</sub> = 0V f = 1.0MHz		3550		pF
Output Capacitance	C <sub>OSS</sub>			710		pF
Reverse Transfer Capacitance	C <sub>RSS</sub>			420		pF
<b>SWITCHING CHARACTERISTICS<sup>b</sup></b>						
Turn-On Delay Time	t <sub>D(ON)</sub>	V <sub>DD</sub> = -15V I <sub>D</sub> = -14 A V <sub>GS</sub> = -10V R <sub>GEN</sub> = 3ohm		40		ns
Rise Time	t <sub>r</sub>			70		ns
Turn-Off Delay Time	t <sub>D(OFF)</sub>			345		ns
Fall Time	t <sub>f</sub>			125		ns
Total Gate Charge	Q <sub>g</sub>	V <sub>DS</sub> = -15V, I <sub>D</sub> = -14A, V <sub>GS</sub> = -10V		87		nC
		V <sub>DS</sub> = -15V, I <sub>D</sub> = -14A, V <sub>GS</sub> = -4.5V		42		nC
Gate-Source Charge	Q <sub>gs</sub>	V <sub>DS</sub> = -15V, I <sub>D</sub> = -14A		9		nC
Gate-Drain Charge	Q <sub>gd</sub>	V <sub>GS</sub> = -10V		20		nC

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## ELECTRICAL CHARACTERISTICS ( $T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Condition	Min	Typ	Max	Unit
<b>DRAIN-SOURCE DIODE CHARACTERISTICS<sup>a</sup></b>						
Diode Forward Voltage	$V_{SD}$	$V_{GS} = 0\text{V}, I_S = -10\text{A}$		-0.7	-1.2	V

### Notes

- a. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
- b. Guaranteed by design, not subject to production testing.

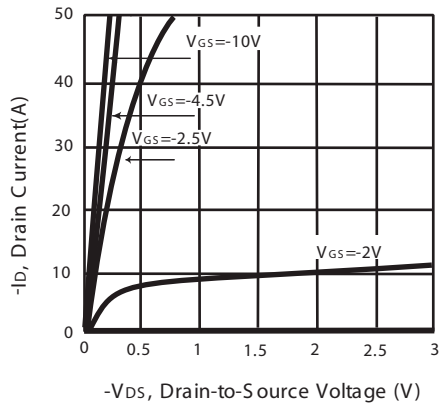


Figure 1. Output Characteristics

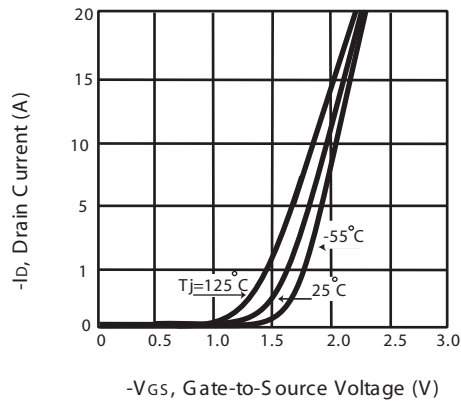


Figure 2. Transfer Characteristics

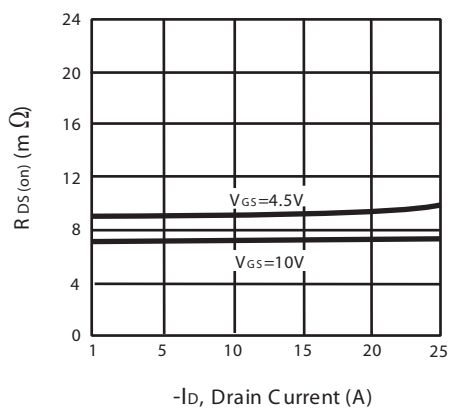


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

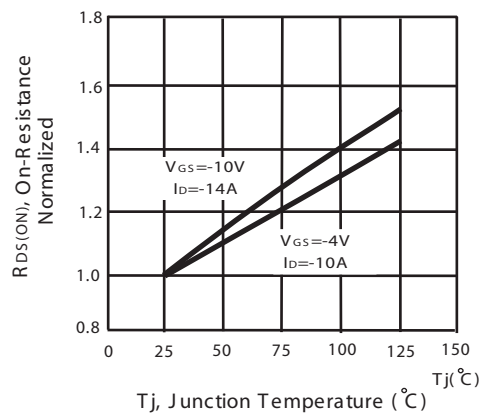


Figure 4. On-Resistance Variation with Drain Current and Temperature

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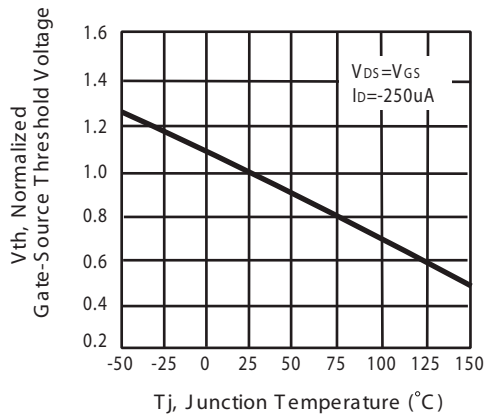


Figure 5. Gate Threshold Variation with Temperature

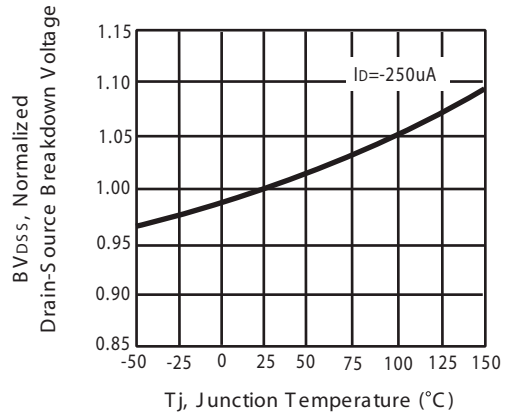


Figure 6. Breakdown Voltage Variation with Temperature

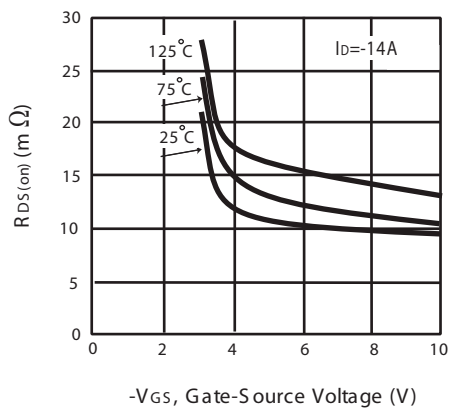


Figure 7. On-Resistance vs. Gate-Source Voltage

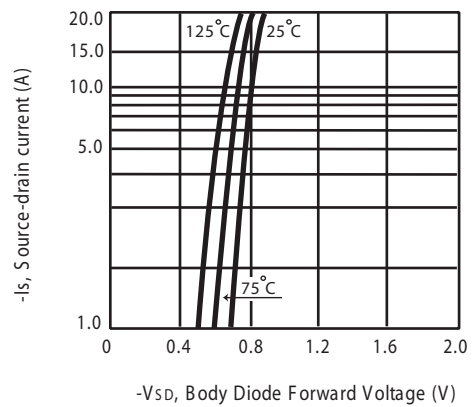


Figure 8. Body Diode Forward Voltage Variation with Source Current

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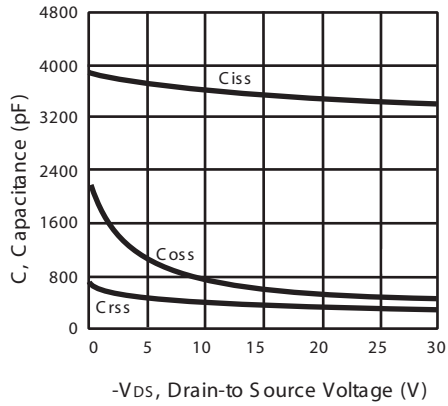


Figure 9. Capacitance

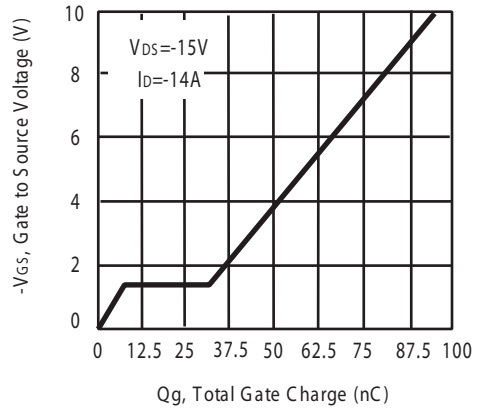


Figure 10. Gate Charge

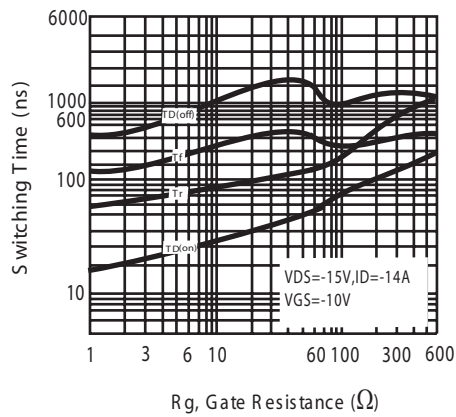


Figure 11. switching characteristics

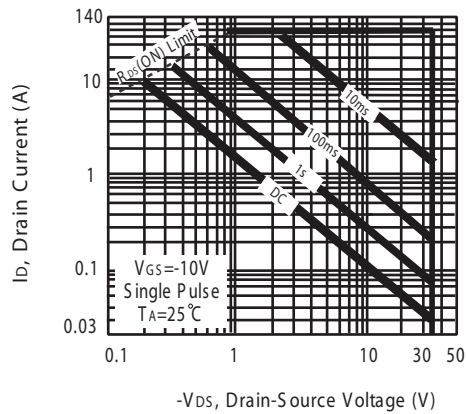


Figure 12. Maximum Safe Operating Area

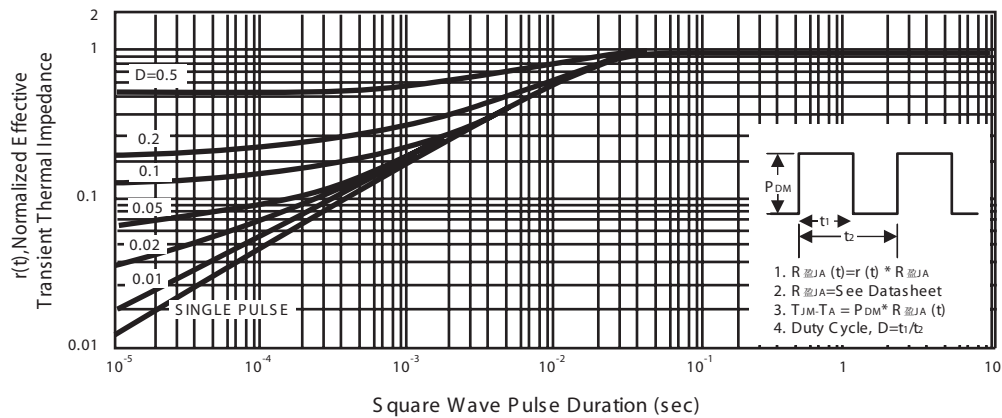
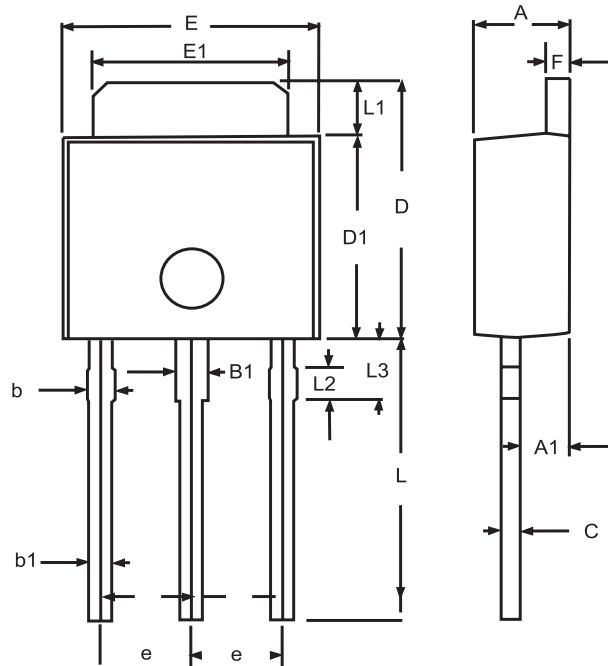


Figure 13. Normalized Thermal Transient Impedance Curve

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## PACKAGE OUTLINE DIMENSIONS

TO-251

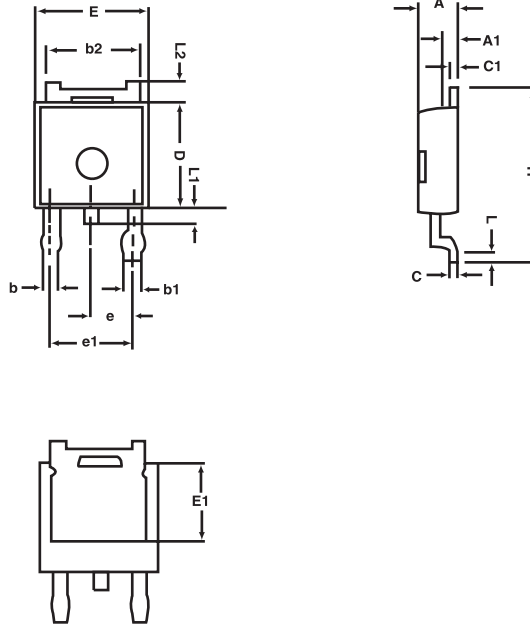


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.20	2.40	0.087	0.095
A1	1.100	1.300	0.043	0.051
B1	0.650	1.050	0.026	0.041
b	0.500	0.900	0.020	0.035
b1	0.400	0.800	0.016	0.32
C	0.400	0.600	0.016	0.024
D	6.700	7.300	0.264	0.287
D1	5.400	5.650	0.213	0.222
E	6.40	6.650	0.252	0.262
e	2.100	2.500	0.083	0.098
F	0.400	0.600	0.016	0.024
L	7.000	8.000	0.276	0.315
L1	1.300	1.700	0.051	0.067
L2	0.700	0.900	0.028	0.035
L3	1.400	1.800	0.055	0.071

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## PACKAGE OUTLINE DIMENSIONS

TO-252

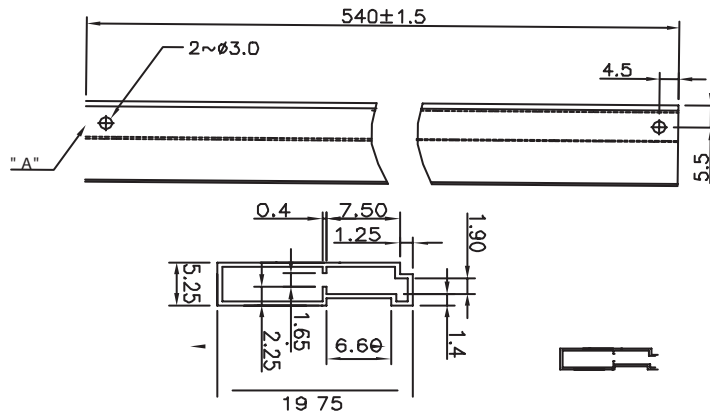


SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	2.25	2.35	0.089	0.093
A1	0.95	1.05	0.037	0.041
b	0.77	0.85	0.030	0.033
b1	0.84	0.94	0.033	0.037
b2	5.30	5.45	0.209	0.215
C	0.49	0.53	0.019	0.021
D	6.00	6.20	0.236	0.244
E	6.40	6.60	0.252	0.260
E1	3.18	3.67	0.125	0.145
e	2.29	BSC	0.090	BSC
H	9.70	10.10	0.382	0.398
L	1.425	1.625	0.056	0.064
L1	0.650	0.850	0.026	0.033
L2	0.600	REF .	0.024	REF .

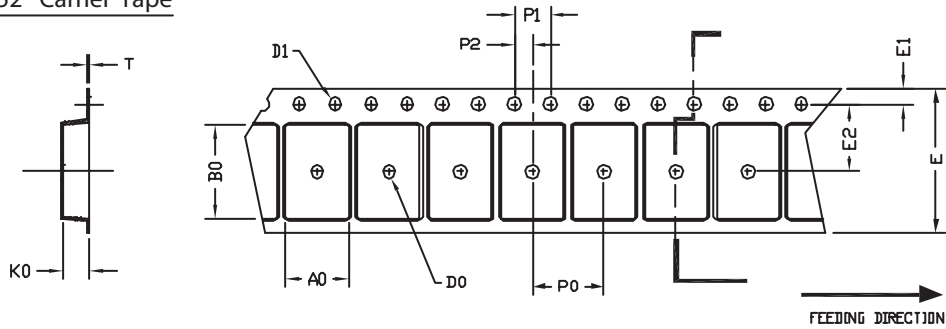
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## TO251 Tube/TO-252 Tape and Reel Data

### TO-251 Tube



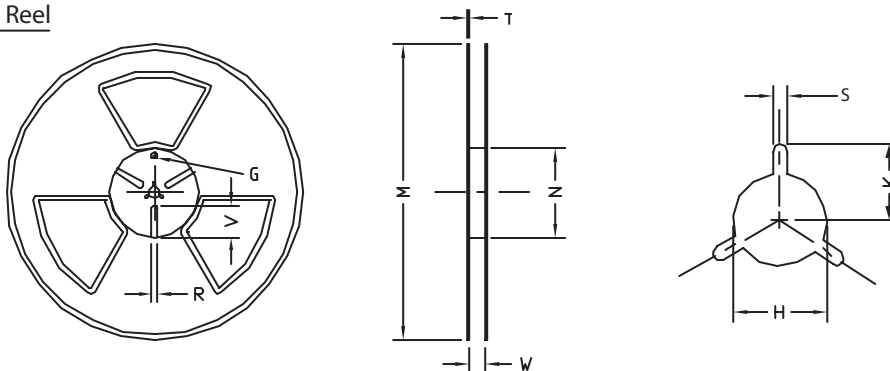
### TO-252 Carrier Tape



UNIT:  $\mu$

PACKAGE	A0	B0	K0	D0	D1	E	E 1	E 2	P0	P1	P2	T
TO-252 (16 $\mu$ I)	6.80 0.1	10.3 0.1	2.50 0.1	榎2	榎1.5 +0.1 -0	16.0 0.3	1.75 0.1	7.5 0.15	8.0 0.1	4.0 0.1	2.0 0.15	0.3 0.05

### TO-252 Reel



UNIT:  $\mu$

TAPE SIZE	REEL SIZE	M	N	W	T	H	K	S	G	R	V
16 $\mu$	榎 330	榎330 0.5	榎97 1.0	17.0 +1.5 -0	2.2	榎13.0 +0.5 -0.2	10.6	2.0 0.5	---	---	---